# Round terminal type with excellent PC board mounting performance





# ■ Typical Specifications

6.2mm Diameter Round Terminal (Radial Type)

Items	Specifications
Rating (max.)	50mA 12V DC
Rating (min.)	10 µA 1V DC
Initial contact resistance	500mΩ max.
Travel (mm)	0.25

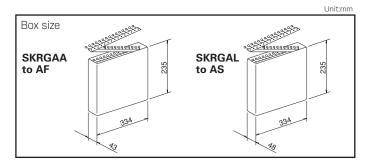
# ■ Product Line

Product No. Operating	Operating direction	Operating life	Stem color	Stem height	Minimum order unit (pcs.)		
i ioddol iio.	force	Operating direction	(5mA 5V DC)		Japan	Export	
SKRGAAD010	1.27N		500,000 cycles	Black	h=4.3mm		
SKRGABD010	1.57N			White			
SKRGACD010	2.55N		200,000 cycles	Gray			
SKRGADD010	1.27N	Top push	500,000 cycles	Black	h=5mm	2.000	2,000
SKRGAED010	1.57N			White			
SKRGAFD010	2.55N		200,000 cycles	Gray			
SKRGALD010	1.27N		500,000 cycles	Black		2,000	2,000
SKRGAMD010	1.57N		- 500,000 cycles -	White	h=7mm		
SKRGAND010	2.55N		200,000 cycles	Gray			
SKRGAQD010	1.27N		EOO OOO ayalaa	Black			
SKRGARD010	1.57N		500,000 cycles	White	h=9.5mm		
SKRGASD010	2.55N		200,000 cycles	Gray			

# Packing Specifications

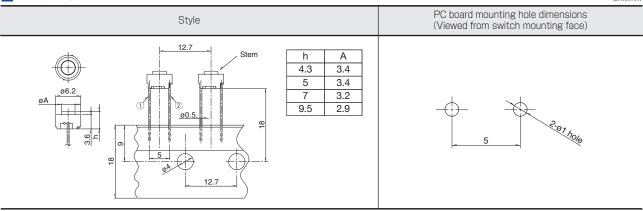
## Radial Taping

Number of packages (pcs.)			Export package measurements	
1 box	1 case / Japan 1 case / export packing		(mm)	
2,000	0000	SKRGAA to AF 353×506×244		
2,000   20,000	20,000	SKRGAL to AS 353×506×269		





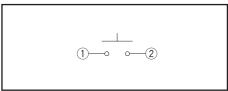
■ Dimensions Unit:mm



# Note

Please use 1.6mm thick PC boards.

# Circuit Diagram



	Sharp Feeling Type							
	Type	Snap-in			Radial			
	Series	SKHL	SKHH	SKQJ	SKQB	SKRG	SKQK	SKRC
	Photo						***	888
	Features	_	_	_	_	Round terminal type	_	Round terminal type
	Water-proof	_	_	_	•	_	_	•
	Dust-proof	_	_	•	•	_	_	•
	IP standard	_	_	_	_	_	_	_
Operatir	Top push	_	_	_	_	•	•	•
directio		•	•	•	•	_	_	_
	W	7.3	7.5	7.5	11.5			
Dimensio (mm)	ons D	7.22	7.85	7.85	11.9	<b>∮</b> 6.2	□6.6	<b>φ</b> 9
(11111)	Н	4.3	7.4	7.3	11.3	See the relevant pages for respective product descriptions	5	13
Operation force coverage	2N to 3N			Ţ	<b>\$</b>	Ţ	Ţ.	1
	Travel (mm)		0.25		0.3	0.25		
G	round terminal	•	•	_	_	_	_	_
Operatin	ng temperature range	-40°C to +90°C -20°C to +70°C -40°C to 95°C -40°C		-40℃ to +90℃	-20℃ to +70℃	-30°C to +85°C		
А	utomotive use	_	_	_	•	•	_	_
	Life Cycle	$\bigstar_2$ $\bigstar_3$ $\bigstar_2$ $\bigstar_2$ $\bigstar_2$				<b>*</b> 2		
	Rating (max.) (Resistive load)	50mA 12V DC						
Electrical	Rating (min.) (Resistive load)	10μA 1V DC						
performance	Insulation resistance	100MΩ min. 100V DC 1min.						
	Voltage proof	250V AC 1min.						
Dzabilita	Vibration	10 to 55 to 10Hz/min., the amplitude is 1.5mm for all the frequencies, in the 3 direction of X, Y and Z for 2 hours respectively						
Durability	Lifetime	Shall be in accordance with individual specifications.						
	Cold	-40°C 96h -30°C 96h -40°C 96h -30°C 96h -40°C			-40℃ 96h			
Environmental performance	Dry heat	90°C	96h	80℃ 96h	90°C	96h	80°C 96h	90°C 96h
	Damp heat	60°C, 90 to 95%RH 96h 60°C, 90 to 95%RH 1,000h 60°C, 90 to 95			95%RH 96h	60°C, 90 to 95%RH 1,000h		
	Page	193	195	200	202	246	248	249

W: Width. The most outer dimension excluding terminal portion.

 $\mathsf{D}:\mathsf{Depth}.$  The most outer dimension excluding terminal portion.  $\mathsf{H}:\mathsf{Height}.$  The minimum dimension if there are variances.

### Notes

- 1. The automotive operating temperature range to be individually discussed upon request.
- 2. Indicates applicability to all products in the series, while  $\bigcirc$  indicates applicability to some products in the series.

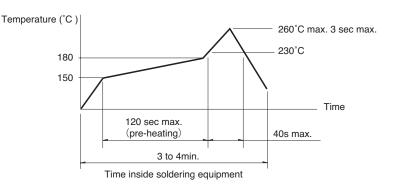


# TACT Switch™ Soldering Conditions

### Condition for Reflow

Available for Surface Mount Type.

- 1. Temperature measurement: Thermocouple  $\phi$  0.1 to 0.2 CA (K) or CC (T) at solder joints (copper foil surface).
  - A heat resistive tape should be used to fix thermocouple.
- 2. Temperature profile



### Notes

- The above temperature shall be measured of the top of switch. There are cases where the PC board's temperature greatly differs from that of the switch, depending on the material, size, thickness of PC boards and others.
  The above-stated conditions shall also apply to switch surface temperatures.
- Soldering conditions differ depending on reflow soldering machines. Prior verification of soldering condition is highly recommended.

### Conditions for Auto-dip

Available for Snap-in Type and Radial Type.

	3.
Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Duration of immersion	5s max.
Number of soldering	2times max.

## SKHH, SKPD Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 110°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Duration of immersion	5s max.
Number of soldering	2times max.

### SKQJ, SKQK, SKEG Series

Items	Condition
Flux built-up	Mounting surface should not be exposed to flux
Preheating temperature	Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	45s max.
Soldering temperature	255℃ max.
Duration of immersion	5s max.
Number of soldering	2times max.

# Manual Soldering

Items	Condition
Soldering temperature	350℃ max.
Duration of soldering	3s max.
Capacity of soldering iron	60W max.

### SKHH, SKHW, SKRG, SKPD Series

Items	Condition
Soldering temperature	360°C max.
Duration of soldering	3s max.
Capacity of soldering iron	60W max.

### SKTD, SKTG, SKQJ, SKQK, SKEG Series

Items	Condition
Soldering temperature	350°C max.
Duration of soldering	3s max.
Capacity of soldering iron	20W max.

### Notes

- 1. Prevent flux penetration from the top side of the TACT Switch™.
- 2. Switch terminals and a PC board should not be coated with flux prior to soldering.
- 3. The second soldering should be done after the switch is stable with normal temperature.
- 4. Use the flux with a specific gravity of min 0.81. (EC-19S-8 by TAMURA Corporation, or equivalents.)

